Material declaration form

General Information

IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information	*: Required Field	

Supplier Information

Company name*	STMicroelectronics	Response Date*	2025-04-10
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by
MDF Champion
Date: 2025.04.10
14:51:04 GMT+08:00

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32F767IIT6	201T*451XXXZ	A	9991	2025-04-10
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	1897	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFP	24x24	176	Gull wing	
Comment	Package : 1T LQFP 176 24x24x1.4 0110489			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false

Exemption Id.	**Description**
,	

QueryList : REACH-21st January 2025				**Response**
QUERY				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**201T*451XXXZ**		1896.5928		6000000.0	1000000.0
Homogeneous material	**Material group**	**Mass**	**Unit of measure**	**Level**	**Substance category**	**Substance**	**CAS**	**Exempt**	**Mass**	**Unit of measure**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	27.154	mg	supplier	die	Silicon (Si)	7440-21-3		26.795	mg	986778	14128.11
				supplier	metallization	Aluminium (Al)	7429-90-5		0.033	mg	1221	17.48
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	203	2.91
				supplier	metallization	Tungsten (W)	7440-33-7		0.006	mg	203	2.91
				supplier	Passivation	Silicon Nitride	12033-89-5		0.022	mg	814	11.65
				supplier	Passivation	Silicon Oxide	7631-86-9		0.293	mg	10781	154.36
Leadframe (Cu - Ag plated)	M-011 Other inorganic materials	666.052	mg	supplier	Alloy	Copper (CU)	7440-50-8		626.402	mg	940470	330277.50
				supplier	Alloy	Nickel (Ni)	7440-02-0		24.780	mg	37204	13065.43
				supplier	Alloy	Silicon (Si)	7440-21-3		5.370	mg	8062	2831.24
				supplier	Alloy	Silver (Ag)	7440-22-4		8.260	mg	12402	4355.38
				supplier	Alloy	Magnesium (Mg)	7439-95-4		1.240	mg	1862	653.90
Glue (EN4900G)	Precious metals	5.209	mg	supplier	Glue or tape	Silver (Ag)	7440-22-4		3.933	mg	755000	2073.57
				supplier	Glue or tape	Cresol Novolac Epoxy Resins	Proprietary		0.130	mg	25000	68.66
				supplier	Glue or tape	Diacrylate	Proprietary		0.443	mg	85000	233.45
				supplier	Glue or tape	Dicyclopentenyl group containing Acrylate	Proprietary		0.286	mg	55000	151.05
				supplier	Glue or tape	Butadiene copolymer	Proprietary		0.052	mg	10000	27.46
				supplier	Glue or tape	Polybutadiene epoxidized derivative	Proprietary		0.286	mg	55000	151.05
				supplier	Glue or tape	Peroxy Ketals	Proprietary		0.026	mg	5000	13.73
				supplier	Glue or tape	Substitutedalkoxyalkyl trimethoxysilane	Proprietary		0.026	mg	5000	13.73
				supplier	Glue or tape	Methacrylate multialkoxysubstitutedalkyl ester	Proprietary		0.026	mg	5000	13.73
Bonding Wire (Cu)	Precious metals	2.099	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		2.026	mg	965500	1068.36
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.065	mg	31000	34.30
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.007	mg	3500	3.87
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	1180.184	mg	supplier	Molding Compound	2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4'-diy	85954-11-6		47.207	mg	40000	24890.61
				supplier	Molding Compound	Epoxy resin	Proprietary		23.604	mg	20000	12445.31
				supplier	Molding Compound	Phenol Resin	Proprietary		88.514	mg	75000	46669.90
				supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		837.341	mg	709500	441497.25
				supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		177.028	mg	150000	93339.80
				supplier	Molding Compound	Carbon black	1333-86-4		6.491	mg	5500	3422.46
Plating (Sn)	M-011 Other inorganic materials	15.895	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		15.893	mg	999900	8379.98
				supplier	Matte Sn	Impurities	Proprietary		0.002	mg	100	0.84